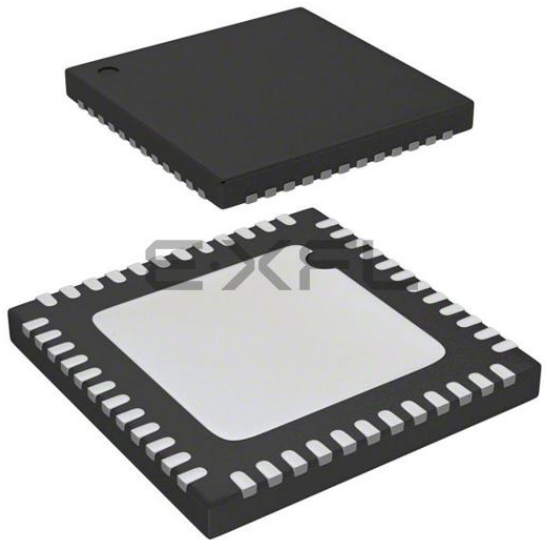

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D - 12b SAR
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TJ)
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	48-QFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32jg12b500f1024im48-c

3.2 Power

The EFM32JG12 has an Energy Management Unit (EMU) and efficient integrated regulators to generate internal supply voltages. Only a single external supply voltage is required, from which all internal voltages are created. An optional integrated DC-DC buck regulator can be utilized to further reduce the current consumption. The DC-DC regulator requires one external inductor and one external capacitor.

The EFM32JG12 device family includes support for internal supply voltage scaling, as well as two different power domains groups for peripherals. These enhancements allow for further supply current reductions and lower overall power consumption.

AVDD and VREGVDD need to be 1.8 V or higher for the MCU to operate across all conditions; however the rest of the system will operate down to 1.62 V, including the digital supply and I/O. This means that the device is fully compatible with 1.8 V components. Running from a sufficiently high supply, the device can use the DC-DC to regulate voltage not only for itself, but also for other PCB components, supplying up to a total of 200 mA.

3.2.1 Energy Management Unit (EMU)

The Energy Management Unit manages transitions of energy modes in the device. Each energy mode defines which peripherals and features are available and the amount of current the device consumes. The EMU can also be used to turn off the power to unused RAM blocks, and it contains control registers for the DC-DC regulator and the Voltage Monitor (VMON). The VMON is used to monitor multiple supply voltages. It has multiple channels which can be programmed individually by the user to determine if a sensed supply has fallen below a chosen threshold.

3.2.2 DC-DC Converter

The DC-DC buck converter covers a wide range of load currents and provides up to 90% efficiency in energy modes EM0, EM1, EM2 and EM3, and can supply up to 200 mA to the device and surrounding PCB components. Protection features include programmable current limiting, short-circuit protection, and dead-time protection. The DC-DC converter may also enter bypass mode when the input voltage is too low for efficient operation. In bypass mode, the DC-DC input supply is internally connected directly to its output through a low resistance switch. Bypass mode also supports in-rush current limiting to prevent input supply voltage droops due to excessive output current transients.

3.2.3 Power Domains

The EFM32JG12 has two peripheral power domains for operation in EM2 and lower. If all of the peripherals in a peripheral power domain are configured as unused, the power domain for that group will be powered off in the low-power mode, reducing the overall current consumption of the device.

Table 3.1. Peripheral Power Subdomains

Peripheral Power Domain 1	Peripheral Power Domain 2
ACMP0	ACMP1
PCNT0	PCNT1
ADC0	PCNT2
LETIMER0	CSEN
LESENSE	DAC0
APORT	LEUART0
-	I2C0
-	I2C1
-	IDAC

3.12 Configuration Summary

The features of the EFM32JG12 are a subset of the feature set described in the device reference manual. The table below describes device specific implementation of the features. Remaining modules support full configuration.

Table 3.2. Configuration Summary

Module	Configuration	Pin Connections
USART0	IrDA SmartCard	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	IrDA I^2S SmartCard	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	IrDA SmartCard	US2_TX, US2_RX, US2_CLK, US2_CS
USART3	IrDA I^2S SmartCard	US3_TX, US3_RX, US3_CLK, US3_CS
TIMER0	with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	-	TIM1_CC[3:0]
WTIMER0	with DTI	WTIM0_CC[2:0], WTIM0_CDTI[2:0]
WTIMER1	-	WTIM1_CC[3:0]

4. Electrical Specifications

4.1 Electrical Characteristics

All electrical parameters in all tables are specified under the following conditions, unless stated otherwise:

- Typical values are based on T_{AMB}=25 °C and V_{DD}= 3.3 V, by production test and/or technology characterization.
- Minimum and maximum values represent the worst conditions across supply voltage, process variation, and operating temperature, unless stated otherwise.

Refer to 4.1.2.1 General Operating Conditions for more details about operational supply and temperature limits.

4.1.1 Absolute Maximum Ratings

Stresses above those listed below may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability. For more information on the available quality and reliability data, see the Quality and Reliability Monitor Report at http://www.silabs.com/support/quality/pages/default.aspx.

Table 4.1. Absolute Maximum Ratings

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Storage temperature range	T_{STG}		-50	—	150	°C
Voltage on any supply pin	V_{DDMAX}		-0.3	—	3.8	V
Voltage ramp rate on any supply pin	$V_{DDRAMPMAX}$		—	—	1	V / µs
DC voltage on any GPIO pin	V_{DIGPIN}	5V tolerant GPIO pins[1]	-0.3	—	Min of 5.25 and IOVDD +2	V
		Non-5V tolerant GPIO pins	-0.3	—	IOVDD+0.3	V
Voltage on HFXO pins	$V_{HFXOPIN}$		-0.3	—	1.4	V
Total current into VDD power lines	I_{VDDMAX}	Source	—	—	200	mA
Total current into VSS ground lines	I_{VSSMAX}	Sink	—	—	200	mA
		Sink	—	—	200	mA
Current per I/O pin	I_{IOMAX}	Sink	—	—	50	mA
		Source	—	—	50	mA
Current for all I/O pins	$I_{IOALLMAX}$	Sink	—	—	200	mA
		Source	—	—	200	mA
Junction temperature	T_J	-G grade devices	-40	—	105	°C
		-I grade devices	-40	—	125	°C

Note:

1. When a GPIO pin is routed to the analog module through the APORT, the maximum voltage = IOVDD.

4.1.5 Current Consumption

4.1.5.1 Current Consumption 3.3 V without DC-DC Converter

Unless otherwise indicated, typical conditions are: VREGVDD = AVDD = DVDD = 3.3 V. T_{OP} = 25 °C. DCDC is off. Minimum and maximum values in this table represent the worst conditions across supply voltage and process variation at T_{OP} = 25 °C.

Table 4.5. Current Consumption 3.3 V without DC-DC Converter

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM0 mode with all peripherals disabled	I_{ACTIVE}	38.4 MHz crystal, CPU running while loop from flash[1]	—	126	—	µA/MHz
		38 MHz HFRCO, CPU running Prime from flash	—	99	—	µA/MHz
		38 MHz HFRCO, CPU running while loop from flash	—	99	TBD	µA/MHz
		38 MHz HFRCO, CPU running CoreMark from flash	—	124	—	µA/MHz
		26 MHz HFRCO, CPU running while loop from flash	—	102	TBD	µA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	280	TBD	µA/MHz
Current consumption in EM0 mode with all peripherals disabled and voltage scaling enabled	I_{ACTIVE_VS}	19 MHz HFRCO, CPU running while loop from flash	—	88	—	µA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	234	—	µA/MHz
Current consumption in EM1 mode with all peripherals disabled	I_{EM1}	38.4 MHz crystal[1]	—	76	—	µA/MHz
		38 MHz HFRCO	—	50	TBD	µA/MHz
		26 MHz HFRCO	—	52	TBD	µA/MHz
		1 MHz HFRCO	—	230	TBD	µA/MHz
Current consumption in EM1 mode with all peripherals disabled and voltage scaling enabled	I_{EM1_VS}	19 MHz HFRCO	—	47	—	µA/MHz
		1 MHz HFRCO	—	193	—	µA/MHz
Current consumption in EM2 mode, with votage scaling enabled.	I_{EM2_VS}	Full 256 kB RAM retention and RTCC running from LFXO	—	2.9	—	µA
		Full 256 kB RAM retention and RTCC running from LFRCO	—	3.2	—	µA
		16 kB (1 bank) RAM retention and RTCC running from LFRCO[2]	—	2.1	TBD	µA
Current consumption in EM3 mode, with voltage scaling enabled.	I_{EM3_VS}	Full 256 kB RAM retention and CRYOTIMER running from ULFRCO	—	2.56	TBD	µA
Current consumption in EM4H mode, with voltage scaling enabled.	I_{EM4H_VS}	128 byte RAM retention, RTCC running from LFXO	—	1.0	—	µA
		128 byte RAM retention, CRYOTIMER running from ULFRCO	—	0.45	—	µA
		128 byte RAM retention, no RTCC	—	0.43	TBD	µA

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM4S mode	I_{EM4S}	No RAM retention, no RTCC	—	0.07	TBD	µA

Note:

1. CMU_HFXOCTRL_LOWPOWER=1.
2. CMU_LFRCOCTRL_ENVREF = 1, CMU_LFRCOCTRL_VREFUPDATE = 1

4.1.8.4 High-Freqency RC Oscillator (HFRCO)

Table 4.13. High-Freqency RC Oscillator (HFRCO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Frequency accuracy	f_{HFRCO_ACC}	At production calibrated frequencies, across supply voltage and temperature	TBD	—	TBD	%
Start-up time	t_{HFRCO}	$f_{HFRCO} \geq 19$ MHz	—	300	—	ns
		$4 < f_{HFRCO} < 19$ MHz	—	1	—	µs
		$f_{HFRCO} \leq 4$ MHz	—	2.5	—	µs
Maximum DPLL lock time[1]	t_{DPLL_LOCK}	f_{REF} = 32.768 kHz, f_{HFRCO} = 39.98 MHz, N = 1219, M = 0	—	183	—	µs
Current consumption on all supplies	I_{HFRCO}	f_{HFRCO} = 38 MHz	—	244	TBD	µA
		f_{HFRCO} = 32 MHz	—	204	TBD	µA
		f_{HFRCO} = 26 MHz	—	173	TBD	µA
		f_{HFRCO} = 19 MHz	—	143	TBD	µA
		f_{HFRCO} = 16 MHz	—	123	TBD	µA
		f_{HFRCO} = 13 MHz	—	110	TBD	µA
		f_{HFRCO} = 7 MHz	—	85	TBD	µA
		f_{HFRCO} = 4 MHz	—	32	TBD	µA
		f_{HFRCO} = 2 MHz	—	31	TBD	µA
		f_{HFRCO} = 1 MHz	—	30	TBD	µA
		f_{HFRCO} = 40 MHz, DPLL enabled	—	385	TBD	µA
		f_{HFRCO} = 32 MHz, DPLL enabled	—	310	—	µA
		f_{HFRCO} = 16 MHz, DPLL enabled	—	203	—	µA
		f_{HFRCO} = 4 MHz, DPLL enabled	—	95	—	µA
		f_{HFRCO} = 1 MHz, DPLL enabled	—	79	—	µA
Coarse trim step size (% of period)	SS_{HFRCO_COARSE}		—	0.8	—	%
Fine trim step size (% of period)	SS_{HFRCO_FINE}		—	0.1	—	%
Period jitter	PJ_{HFRCO}		—	0.2	—	% RMS

Note:

1. Maximum DPLL lock time ~= 6 x (M+1) x t_{REF}, where t_{REF} is the reference clock period.

4.1.9 Flash Memory Characteristics[3]

Table 4.16. Flash Memory Characteristics[3]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Flash erase cycles before failure	EC_{FLASH}		10000	—	—	cycles
Flash data retention	RET_{FLASH}	T_{AMB} ≤ 85 °C	10	—	—	years
		T_{AMB} ≤ 125 °C	10	—	—	years
Word (32-bit) programming time	t_{W_PROG}		20	24.4	30	µs
Page erase time	t_{PERASE}		20	26.4	35	ms
Mass erase time[1]	t_{MERASE}		20	26.5	35	ms
Device erase time[2]	t_{DERASE}	T_{AMB} ≤ 85 °C	—	69	100	ms
		T_{AMB} ≤ 125 °C	—	69	110	ms
Page erase current[4]	I_{ERASE}		—	—	1.6	mA
Write current[4]	I_{WRITE}		—	—	3.8	mA
Supply voltage during flash erase and write	V_{FLASH}		1.62	—	TBD	V

Note:

1. Mass erase is issued by the CPU and erases all flash.
2. Device erase is issued over the AAP interface and erases all flash, SRAM, the Lock Bit (LB) page, and the User data page Lock Word (ULW).
3. Flash data retention information is published in the Quarterly Quality and Reliability Report.
4. Measured at 25 °C.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit

Note:

1. ACMPVDD is a supply chosen by the setting in ACMPn_CTRL_PWRSEL and may be IOVDD, AVDD or DVDD.
2. The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference. $I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF}$.
3. ± 100 mV differential drive.
4. In ACMPn_CTRL register.
5. In ACMPn_HYSTERESIS register.
6. In ACMPn_INPUTSEL register.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Open-loop gain	G_{OL}	DRIVESTRENGTH = 3	—	135	—	dB
		DRIVESTRENGTH = 2	—	137	—	dB
		DRIVESTRENGTH = 1	—	121	—	dB
		DRIVESTRENGTH = 0	—	109	—	dB
Loop unit-gain frequency[7]	UGF	DRIVESTRENGTH = 3, Buffer connection	—	3.38	—	MHz
		DRIVESTRENGTH = 2, Buffer connection	—	0.9	—	MHz
		DRIVESTRENGTH = 1, Buffer connection	—	132	—	kHz
		DRIVESTRENGTH = 0, Buffer connection	—	34	—	kHz
		DRIVESTRENGTH = 3, 3x Gain connection	—	2.57	—	MHz
		DRIVESTRENGTH = 2, 3x Gain connection	—	0.71	—	MHz
		DRIVESTRENGTH = 1, 3x Gain connection	—	113	—	kHz
		DRIVESTRENGTH = 0, 3x Gain connection	—	28	—	kHz
Phase margin	PM	DRIVESTRENGTH = 3, Buffer connection	—	67	—	°
		DRIVESTRENGTH = 2, Buffer connection	—	69	—	°
		DRIVESTRENGTH = 1, Buffer connection	—	63	—	°
		DRIVESTRENGTH = 0, Buffer connection	—	68	—	°
Output voltage noise	N_{OUT}	DRIVESTRENGTH = 3, Buffer connection, 10 Hz - 10 MHz	—	146	—	µVrms
		DRIVESTRENGTH = 2, Buffer connection, 10 Hz - 10 MHz	—	163	—	µVrms
		DRIVESTRENGTH = 1, Buffer connection, 10 Hz - 1 MHz	—	170	—	µVrms
		DRIVESTRENGTH = 0, Buffer connection, 10 Hz - 1 MHz	—	176	—	µVrms
		DRIVESTRENGTH = 3, 3x Gain connection, 10 Hz - 10 MHz	—	313	—	µVrms
		DRIVESTRENGTH = 2, 3x Gain connection, 10 Hz - 10 MHz	—	271	—	µVrms
		DRIVESTRENGTH = 1, 3x Gain connection, 10 Hz - 1 MHz	—	247	—	µVrms
		DRIVESTRENGTH = 0, 3x Gain connection, 10 Hz - 1 MHz	—	245	—	µVrms

4.1.21 USART SPI

SPI Master Timing

Table 4.30. SPI Master Timing

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCLK period [1] [3] [2]	t_{SCLK}		2 * $t_{HFPERCLK}$	—	—	ns
CS to MOSI [1] [3]	t_{CS_MO}		0	—	13.3	ns
SCLK to MOSI [1] [3]	t_{SCLK_MO}		0	—	8	ns
MISO setup time [1] [3]	t_{SU_MI}	IOVDD = 1.62 V	90	—	—	ns
		IOVDD = 3.0 V	40	—	—	ns
MISO hold time [1] [3]	t_{H_MI}		10	—	—	ns

Note:
1. Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0).
2. $t_{HFPERCLK}$ is one period of the selected HFPERCLK.
3. Measurement done with 8 pF output loading at 10% and 90% of V_{DD} (figure shows 50% of V_{DD}).

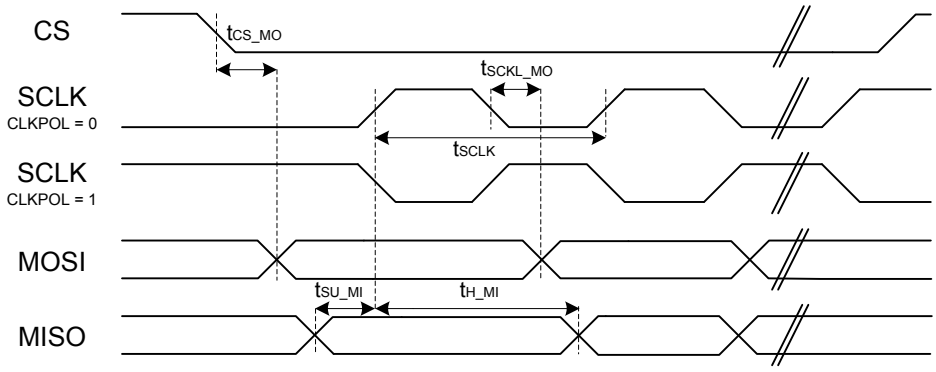

Figure 4.1. SPI Master Timing Diagram

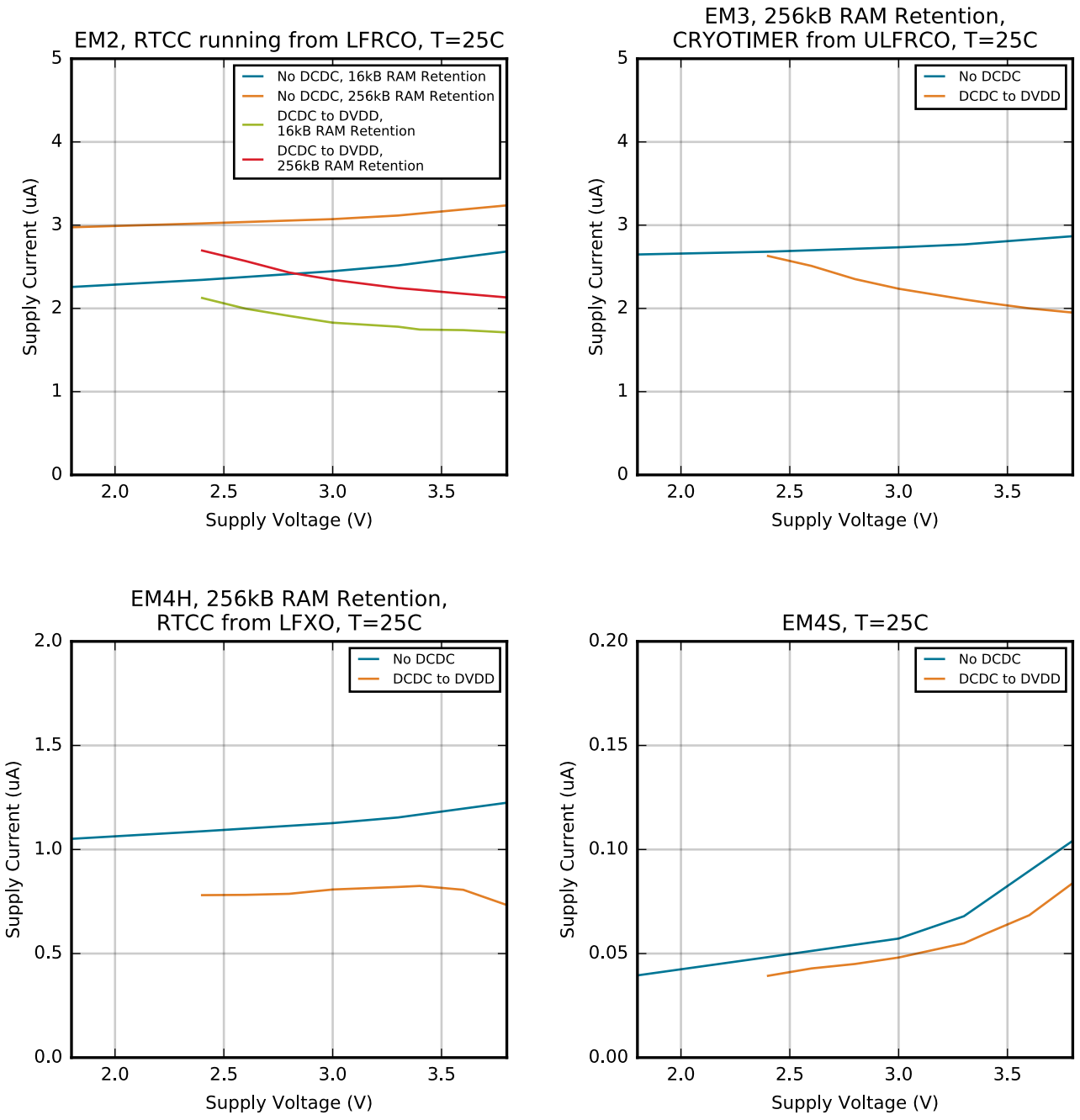

Figure 4.7. EM2, EM3, EM4H and EM4S Typical Supply Current vs. Supply

4.2.2 DC-DC Converter

Default test conditions: CCM mode, LDCDC = 4.7 µH, CDCDC = 4.7 µF, VDCDC_I = 3.3 V, VDCDC_O = 1.8 V, FDCDC_LN = 7 MHz

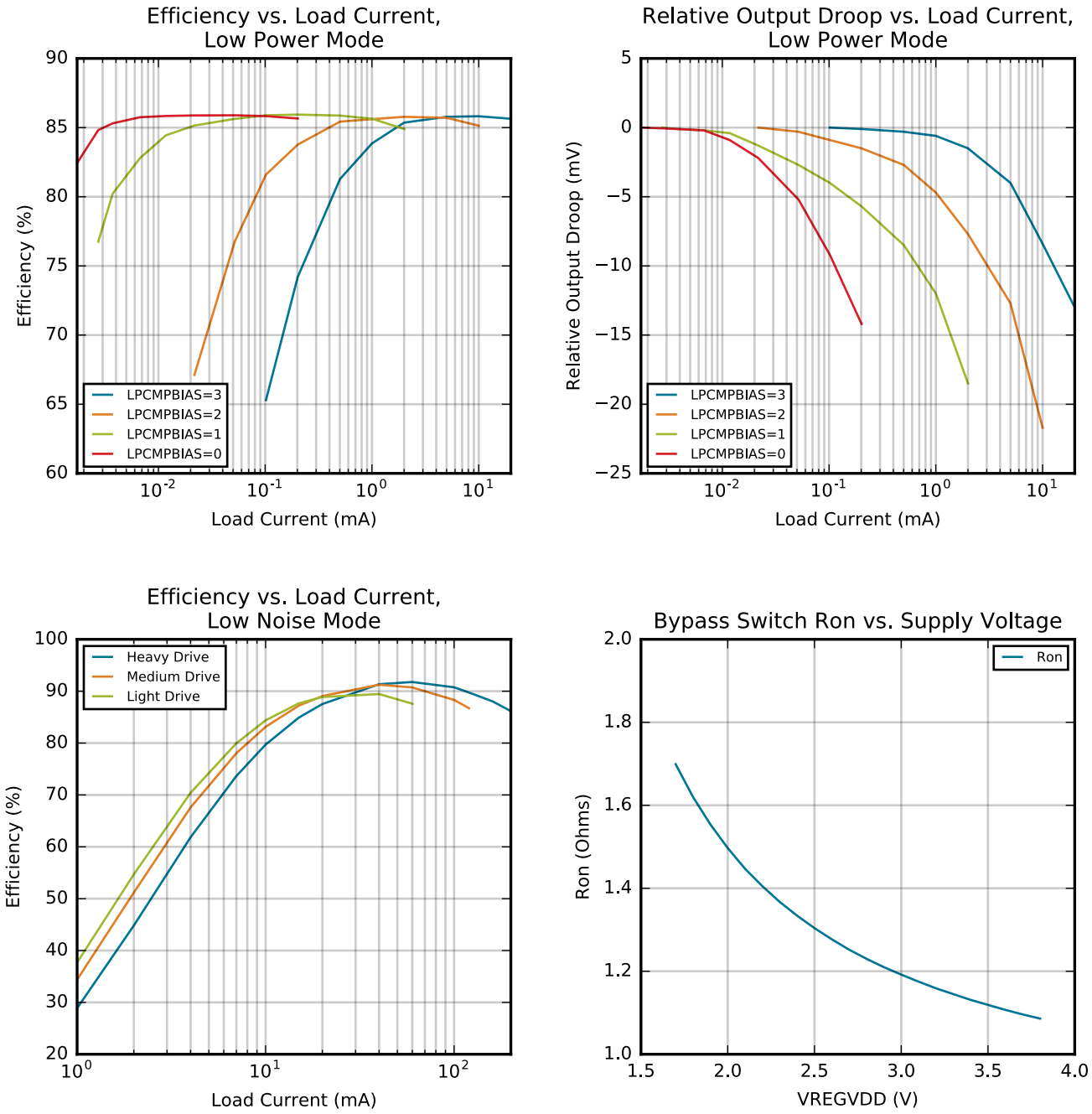

Figure 4.8. DC-DC Converter Typical Performance Characteristics

5. Typical Connection Diagrams

5.1 Power

Typical power supply connections for direct supply, without using the internal DC-DC converter, are shown in Figure 5.1 EFM32JG12 Typical Application Circuit, Direct Supply, No DC-DC Converter on page 59.

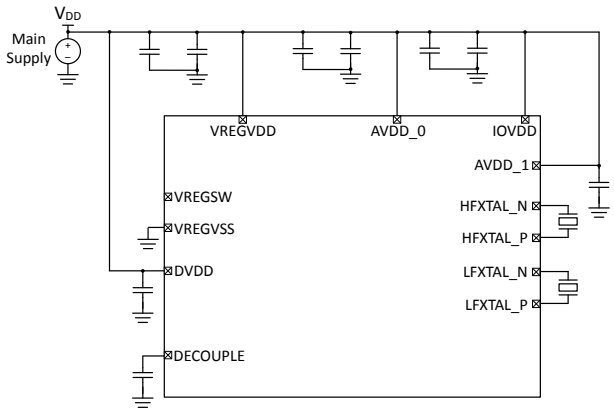

Figure 5.1. EFM32JG12 Typical Application Circuit, Direct Supply, No DC-DC Converter

A typical application circuit using the internal DC-DC converter is shown in Figure 5.2 EFM32JG12 Typical Application Circuit Using the DC-DC Converter on page 59. The MCU operates from the DC-DC converter supply.

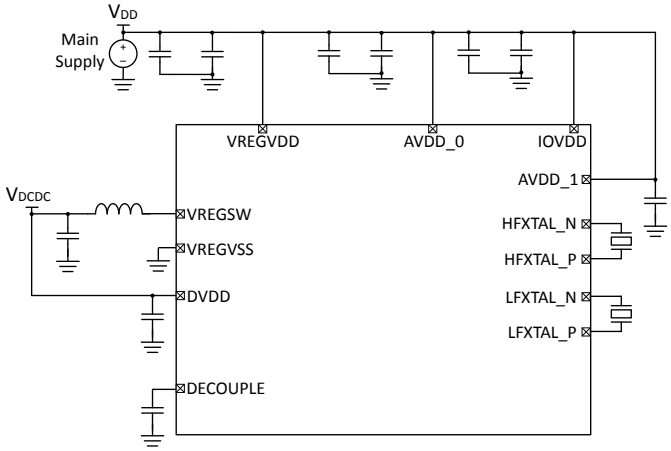

Figure 5.2. EFM32JG12 Typical Application Circuit Using the DC-DC Converter

5.2 Other Connections

Other components or connections may be required to meet the system-level requirements. Application Note AN0002: "Hardware Design Considerations" contains detailed information on these connections. Application Notes can be accessed on the Silicon Labs website (www.silabs.com/32bit-appnotes).

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
B4	PC4	BUSBY BUSAX	WTIM0_CC0 #24 WTIM0_CC1 #22 WTIM0_CC2 #20 WTIM0_CDTI0 #16 WTIM0_CDTI1 #14 WTIM0_CDTI2 #12 WTIM1_CC0 #8 WTIM1_CC1 #6 WTIM1_CC2 #4 WTIM1_CC3 #2 PCNT1_S0IN #17 PCNT1_S1IN #16 PCNT2_S0IN #17 PCNT2_S1IN #16	US3_TX #22 US3_RX #21 US3_CLK #20 US3_CS #19 US3_CTS #18 US3_RTS #17 I2C1_SDA #17 I2C1_SCL #16	
B5	PC1	BUSAY BUSBX	WTIM0_CC0 #21 WTIM0_CC1 #19 WTIM0_CC2 #17 WTIM0_CDTI0 #13 WTIM0_CDTI1 #11 WTIM0_CDTI2 #9 WTIM1_CC0 #5 WTIM1_CC1 #3 WTIM1_CC2 #1 PCNT1_S0IN #14 PCNT1_S1IN #13 PCNT2_S0IN #14 PCNT2_S1IN #13	US3_TX #19 US3_RX #18 US3_CLK #17 US3_CS #16 US3_CTS #15 US3_RTS #14 I2C1_SDA #14 I2C1_SCL #13	
B6	PJ14	BUSACMP1Y BUSACMP1X	PCNT1_S0IN #11 PCNT1_S1IN #10 PCNT2_S0IN #11 PCNT2_S1IN #10	US3_TX #16 US3_RX #15 US3_CLK #14 US3_CS #13 US3_CTS #12 US3_RTS #11 I2C1_SDA #11 I2C1_SCL #10	LES_ALTEX2
B7	PC10	BUSBY BUSAX	TIM0_CC0 #15 TIM0_CC1 #14 TIM0_CC2 #13 TIM0_CDTI0 #12 TIM0_CDTI1 #11 TIM0_CDTI2 #10 TIM1_CC0 #15 TIM1_CC1 #14 TIM1_CC2 #13 TIM1_CC3 #12 WTIM0_CC0 #30 WTIM0_CC1 #28 WTIM0_CC2 #26 WTIM0_CDTI0 #22 WTIM0_CDTI1 #20 WTIM0_CDTI2 #18 WTIM1_CC0 #14 WTIM1_CC1 #12 WTIM1_CC2 #10 WTIM1_CC3 #8 LETIM0_OUT0 #15 LETIM0_OUT1 #14 PCNT0_S0IN #15 PCNT0_S1IN #14 PCNT2_S0IN #19 PCNT2_S1IN #18	US0_TX #15 US0_RX #14 US0_CLK #13 US0_CS #12 US0_CTS #11 US0_RTS #10 US1_TX #15 US1_RX #14 US1_CLK #13 US1_CS #12 US1_CTS #11 US1_RTS #10 LEU0_TX #15 LEU0_RX #14 I2C0_SDA #15 I2C0_SCL #14 I2C1_SDA #19 I2C1_SCL #18	CMU_CLK1 #3 PRS_CH0 #12 PRS_CH9 #15 PRS_CH10 #4 PRS_CH11 #3 ACMP0_O #15 ACMP1_O #15 ETM_TD3 #3 GPIO_EM4WU12

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
E13	PB7	BUSCY BUSDX	WTIM0_CC0 #11 WTIM0_CC1 #9 WTIM0_CC2 #7 WTIM0_CDTI0 #3 WTIM0_CDTI1 #1 PCNT1_S0IN #7 PCNT1_S1IN #6 PCNT2_S0IN #7 PCNT2_S1IN #6	US2_TX #10 US2_RX #9 US2_CLK #8 US2_CS #7 US2_CTS #6 US2_RTS #5 US3_TX #11 US3_RX #10 US3_CLK #9 US3_CS #8 US3_CTS #7 US3_RTS #6 I2C1_SDA #7 I2C1_SCL #6	ETM_TD2 #2
F1	PK2		PCNT1_S0IN #31 PCNT1_S1IN #30 PCNT2_S0IN #31 PCNT2_S1IN #30	US2_TX #31 US2_RX #30 US2_CLK #29 US2_CS #28 US2_CTS #27 US2_RTS #26 US3_TX #31 US3_RX #30 US3_CLK #29 US3_CS #28 US3_CTS #27 US3_RTS #26 I2C1_SDA #31 I2C1_SCL #30	
F2	IOVDD	Digital IO power supply .			
F5	VSS	Ground			
F6	VSS	Ground			
F7	VSS	Ground			
F8	VSS	Ground			
F9	VSS	Ground			
F11	IOVDD	Digital IO power supply .			
F12	PB6	BUSDY BUSCX	WTIM0_CC0 #10 WTIM0_CC1 #8 WTIM0_CC2 #6 WTIM0_CDTI0 #2 WTIM0_CDTI1 #0 PCNT1_S0IN #6 PCNT1_S1IN #5 PCNT2_S0IN #6 PCNT2_S1IN #5	US2_TX #9 US2_RX #8 US2_CLK #7 US2_CS #6 US2_CTS #5 US2_RTS #4 US3_TX #10 US3_RX #9 US3_CLK #8 US3_CS #7 US3_CTS #6 US3_RTS #5 I2C1_SDA #6 I2C1_SCL #5	CMU_CLKI0 #3 ETM_TD1 #2
F13	PI3	BUSADC0Y BUSADC0X	PCNT1_S0IN #5 PCNT1_S1IN #4 PCNT2_S0IN #5 PCNT2_S1IN #4	US2_TX #8 US2_RX #7 US2_CLK #6 US2_CS #5 US2_CTS #4 US2_RTS #3 US3_TX #9 US3_RX #8 US3_CLK #7 US3_CS #6 US3_CTS #5 US3_RTS #4 I2C1_SDA #5 I2C1_SCL #4	LES_ALTEX7 ETM_TD0 #2

Pin		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
G13	PI0	BUSADC0Y BUSADC0X		US2_TX #5 US2_RX #4 US2_CLK #3 US2_CS #2 US2_CTS #1 US2_RTS #0	LES_ALTEX4
H1	PF7	BUSAY BUSBX	TIM0_CC0 #31 TIM0_CC1 #30 TIM0_CC2 #29 TIM0_CDTI0 #28 TIM0_CDTI1 #27 TIM0_CDTI2 #26 TIM1_CC0 #31 TIM1_CC1 #30 TIM1_CC2 #29 TIM1_CC3 #28 WTIM1_CC0 #31 WTIM1_CC1 #29 WTIM1_CC2 #27 WTIM1_CC3 #25 LE-TIM0_OUT0 #31 LE-TIM0_OUT1 #30 PCNT0_S0IN #31 PCNT0_S1IN #30 PCNT1_S0IN #20 PCNT1_S1IN #19	US0_TX #31 US0_RX #30 US0_CLK #29 US0_CS #28 US0_CTS #27 US0_RTS #26 US1_TX #31 US1_RX #30 US1_CLK #29 US1_CS #28 US1_CTS #27 US1_RTS #26 US2_TX #20 US2_RX #19 US2_CLK #18 US2_CS #17 US2_CTS #16 US2_RTS #15 LEU0_TX #31 LEU0_RX #30 I2C0_SDA #31 I2C0_SCL #30	CMU_CLKI0 #1 CMU_CLK0 #7 PRS_CH0 #7 PRS_CH1 #6 PRS_CH2 #5 PRS_CH3 #4 ACMP0_O #31 ACMP1_O #31 GPIO_EM4WU1
H2	PF6	BUSBY BUSAX	TIM0_CC0 #30 TIM0_CC1 #29 TIM0_CC2 #28 TIM0_CDTI0 #27 TIM0_CDTI1 #26 TIM0_CDTI2 #25 TIM1_CC0 #30 TIM1_CC1 #29 TIM1_CC2 #28 TIM1_CC3 #27 WTIM1_CC0 #30 WTIM1_CC1 #28 WTIM1_CC2 #26 WTIM1_CC3 #24 LE-TIM0_OUT0 #30 LE-TIM0_OUT1 #29 PCNT0_S0IN #30 PCNT0_S1IN #29 PCNT1_S0IN #19 PCNT1_S1IN #18	US0_TX #30 US0_RX #29 US0_CLK #28 US0_CS #27 US0_CTS #26 US0_RTS #25 US1_TX #30 US1_RX #29 US1_CLK #28 US1_CS #27 US1_CTS #26 US1_RTS #25 US2_TX #19 US2_RX #18 US2_CLK #17 US2_CS #16 US2_CTS #15 US2_RTS #14 LEU0_TX #30 LEU0_RX #29 I2C0_SDA #30 I2C0_SCL #29	CMU_CLK1 #7 PRS_CH0 #6 PRS_CH1 #5 PRS_CH2 #4 PRS_CH3 #3 ACMP0_O #30 ACMP1_O #30
H5	VSS	Ground			
H6	VSS	Ground			
H7	VSS	Ground			
H8	VSS	Ground			
H9	VSS	Ground			

Alternate	LOCATION								
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
US3_CLK	0: PD10 1: PD11 2: PD12 3: PD13	4: PD14 5: PD15 6: PI2 7: PI3	8: PB6 9: PB7 10: PB8 11: PB9	12: PB10 13: PB11 14: PJ14 15: PJ15	16: PC0 17: PC1 18: PC2 19: PC3	20: PC4 21: PC5 22: PF11 23: PF12	24: PF13 25: PF14 26: PF15 27: PK0	28: PK1 29: PK2 30: PD8 31: PD9	USART3 clock input / output.
US3_CS	0: PD11 1: PD12 2: PD13 3: PD14	4: PD15 5: PI2 6: PI3 7: PB6	8: PB7 9: PB8 10: PB9 11: PB10	12: PB11 13: PJ14 14: PJ15 15: PC0	16: PC1 17: PC2 18: PC3 19: PC4	20: PC5 21: PF11 22: PF12 23: PF13	24: PF14 25: PF15 26: PK0 27: PK1	28: PK2 29: PD8 30: PD9 31: PD10	USART3 chip select input / output.
US3_CTS	0: PD12 1: PD13 2: PD14 3: PD15	4: PI2 5: PI3 6: PB6 7: PB7	8: PB8 9: PB9 10: PB10 11: PB11	12: PJ14 13: PJ15 14: PC0 15: PC1	16: PC2 17: PC3 18: PC4 19: PC5	20: PF11 21: PF12 22: PF13 23: PF14	24: PF15 25: PK0 26: PK1 27: PK2	28: PD8 29: PD9 30: PD10 31: PD11	USART3 Clear To Send hardware flow control input.
US3_RTS	0: PD13 1: PD14 2: PD15 3: PI2	4: PI3 5: PB6 6: PB7 7: PB8	8: PB9 9: PB10 10: PB11 11: PJ14	12: PJ15 13: PC0 14: PC1 15: PC2	16: PC3 17: PC4 18: PC5 19: PF11	20: PF12 21: PF13 22: PF14 23: PF15	24: PK0 25: PK1 26: PK2 27: PD8	28: PD9 29: PD10 30: PD11 31: PD12	USART3 Request To Send hardware flow control output.
US3_RX	0: PD9 1: PD10 2: PD11 3: PD12	4: PD13 5: PD14 6: PD15 7: PI2	8: PI3 9: PB6 10: PB7 11: PB8	12: PB9 13: PB10 14: PB11 15: PJ14	16: PJ15 17: PC0 18: PC1 19: PC2	20: PC3 21: PC4 22: PC5 23: PF11	24: PF12 25: PF13 26: PF14 27: PF15	28: PK0 29: PK1 30: PK2 31: PD8	USART3 Asynchronous Receive. USART3 Synchronous mode Master Input / Slave Output (MISO).
US3_TX	0: PD8 1: PD9 2: PD10 3: PD11	4: PD12 5: PD13 6: PD14 7: PD15	8: PI2 9: PI3 10: PB6 11: PB7	12: PB8 13: PB9 14: PB10 15: PB11	16: PJ14 17: PJ15 18: PC0 19: PC1	20: PC2 21: PC3 22: PC4 23: PC5	24: PF11 25: PF12 26: PF13 27: PF14	28: PF15 29: PK0 30: PK1 31: PK2	USART3 Asynchronous Transmit. Also used as receive input in half duplex communication. USART3 Synchronous mode Master Output / Slave Input (MOSI).
VDAC0_EXT	0: PA1								Digital to analog converter VDAC0 external reference input pin.
VDAC0_OUT0 / OPA0_OUT	0: PA3								Digital to Analog Converter DAC0 output channel number 0.
VDAC0_OUT0ALT / OPA0_OUTALT	0: PA5 1: PD13 2: PD15								Digital to Analog Converter DAC0 alternative output for channel 0.
VDAC0_OUT1 / OPA1_OUT	0: PD14								Digital to Analog Converter DAC0 output channel number 1.
VDAC0_OUT1ALT / OPA1_OUTALT	0: PD12 1: PA2 2: PA4								Digital to Analog Converter DAC0 alternative output for channel 1.

Table 6.7. ACMP1 Bus and Pin Mapping

Port	Bus	CH31	CH30	CH29	CH28	CH27	CH26	CH25	CH24	CH23	CH22	CH21	CH20	CH19	CH18	CH17	CH16	CH15	CH14	CH13	CH12	CH11	CH10	CH9	CH8	CH7	CH6	CH5	CH4	CH3	CH2	CH1	CH0
APORT0X	BUSACMP1X																									PJ15	PJ14						
APORT0Y	BUSACMP1Y																									PJ15	PJ14						
APORT1X	BUSAX		PF14		PF12		PF10		PF8		PF6		PF4		PF2		PF0						PC10		PC8		PC6		PC4		PC2		PC0
APORT1Y	BUSAY	PF15		PF13		PF11		PF9		PF7		PF5		PF3		PF1						PC11		PC9		PC7		PC5		PC3		PC1	
APORT2X	BUSBX	PF15		PF13		PF11		PF9		PF7		PF5		PF3		PF1						PC11		PC9		PC7		PC5		PC3		PC1	
APORT2Y	BUSBY		PF14		PF12		PF10		PF8		PF6		PF4		PF2		PF0						PC10		PC8		PC6		PC4		PC2		PC0
APORT3X	BUSCX		PB14		PB12		PB10		PB8		PB6							PA7	PA6		PA4		PA2		PA0		PD14		PD12		PD10		PD8
APORT3Y	BUSCY	PB15		PB13		PB11		PB9		PB7								PA7		PA5		PA3		PA1		PD15		PD13		PD11		PD9	
APORT4X	BUSDX	PB15		PB13		PB11		PB9		PB7								PA7		PA5		PA3		PA1		PD15		PD13		PD11		PD9	
APORT4Y	BUSDY		PB14		PB12		PB10		PB8		PB6							PA7	PA6		PA4		PA2		PA0		PD14		PD12		PD10		PD8

9. Revision History

9.1 Revision 0.5

2017-02-10

- Updated Feature List and Front Page with latest characterization numbers.
- List of OPNs in Ordering Table consolidated.
- Electrical Characteristics Table Changes
  - All specification tables updated with latest characterization data and production test limits.
  - Split HFRCO/AUXHFRCO table into separate tables for HFRCO and AUXHFRCO.
  - OPAMP, CSEN, and VDAC specification line items updated to match test conditions.
  - Added tables for Analog Port (APORT) and Pulse Counter (PCNT).
- Added Typical Performance Curves for supply current and DCDC parameters.
- Added APORT Connection Diagram.

9.2 Revision 0.2

December 9th, 2016

Initial release.